

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

### Title of Invention

Integrated Circuit Chip Having A Ringed Wiring Layer Interposed  
Between A Contact Layer And A Wiring Grid

Application Number :

Confirmation Number:

First Named Applicant: Thomas Bednar

Attorney Docket Number: BUR920020107US1

Art Unit:

Examiner:

Search string: ( 6202191 or 6185722 or 6184477 or 6182272 or 6035111 or 6028440 or 6002857  
or 5978572 or 5923089 or 5793643 or 5404310 or 5283753 or 5272645 or 5145800  
or 5040144 ).pn

### US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6202191	2001-03-27	Filippi et al			
	2	6185722	2001-02-06	Darden et al			
	3	6184477	2001-02-06	Tanahashi			
	4	6182272	2001-01-30	Andreev et al			
	5	6035111	2000-03-07	Suzuki et al			
	6	6028440	2000-02-22	Roethig et al			
	7	6002857	1999-12-14	Ramachandran			
	8	5978572	1999-11-02	Toyonaga et al			
	9	5923089	1999-07-13	Yao et al			
	10	5793643	1998-08-11	Cai			
	11	5404310	1995-04-04	Mitsuhashi			
	12	5283753	1994-02-01	Schucker et al			
	13	5272645	1993-12-21	Kawakami et al			
	14	5145800	1992-09-08	Arai et al			
	15	5040144	1991-08-13	Pelley et al			

### Signature

Examiner Name	Date